

SGL40T120SMD

1200V 40A FieldStop Trench IGBT

Features

- FieldStop Trench Technology, Positive temperature coefficient
- $V_{CE(sat)}=2.4V @ I_C=40A$
- $t_{tr}=50ns(\text{typ.})$
- High Speed Switching & Low Power Loss
- High Input Impedance

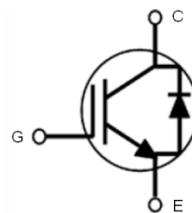
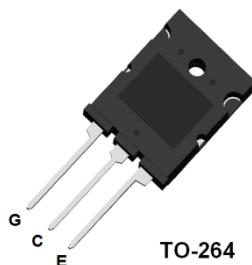
Applications

- PFC, UPS, Welder, PV Inverter

Description

The device is designed by advanced FieldStop Trench technology process. This IGBT offer low $V_{CE(sat)}$, high switching performance and excellent quality for application such as PFC,UPS, Welder, PV Inverter and other switching applications.

Package Type & Internal Circuit



Absolute Maximum Ratings

Symbol	Parameter		Ratings	Unit
V_{CES}	Collector to Emitter Voltage		1200	V
V_{GES}	Gate to Emitter Voltage		± 20	V
I_C	Collector Current	$T_C=25^\circ\text{C}$	80	A
		$T_C=100^\circ\text{C}$	40	A
I_{CM}	Pulsed Collector Current		160	A
I_F	Diode Continuous Forward Current	$T_C=100^\circ\text{C}$	30	A
I_{FM}	Diode Maximum Forward Current		180	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	430	W
		$T_C=100^\circ\text{C}$	180	W
T_J	Operating Junction Temperature Range		-40~+150	°C
T_{STG}	Storage Temperature Range		-40~+150	°C

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{th(J-C)}$ (IGBT)	Thermal Resistance, Junction to case for IGBT	0.29	°C/W
$R_{th(J-C)}$ (Diode)	Thermal Resistance, Junction to case for Diode	1.1	°C/W
$R_{th(J-A)}$	Thermal Resistance, Junction to Ambient	25	°C/W

Electrical Characteristics of IGBT @ $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit	
BV_{CES}	Collector to Emitter Breakdown Voltage	$V_{GE}=0\text{V}, I_C=1\text{mA}$ $I_C=40\text{A}, V_{GE}=15\text{V}$ $I_C=40\text{A}, V_{GE}=15\text{V}, T_C=150\text{ }^\circ\text{C}$	1200	-	-	V	
$V_{CE(\text{sat})}$	Collector to Emitter Saturation Voltage		-	2.4	2.9	V	
			-	2.9	-	V	
$V_{GE(\text{th})}$	Gate Threshold Voltage	$V_{CE}=V_{GE}, I_C=1\text{mA}$	5.0	6.0	7.0	V	
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}$	-	-	1	mA	
I_{GES}	Gate to Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}$	-	-	± 250	nA	

Electrical Characteristics of Diode @ $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=30\text{A}$	-	3.4	3.9	V
		$I_F=30\text{A}, T_C=150\text{ }^\circ\text{C}$	-	2.7	-	V
t_{rr}	Diode Reverse Recovery Time		-	50	-	ns
I_{rr}	Diode Peak Reverse Recovery Current	$I_F=30\text{A}, di/dt=-200\text{A/us}$	-	5.3	-	A
Q_{rr}	Diode Reverse Recovery Charge		-	120	-	nC

Switching Characteristics @ $T_C=25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$I_C=40\text{A}, V_{CC}=600\text{V}, V_{GE}=15\text{V}, R_G=10\Omega, \text{Inductive Load, } T_C=25\text{ }^\circ\text{C}$	-	73	-	ns
t_r	Turn-on Rise Time		-	41	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	269	-	ns
t_f	Turn-off Fall Time		-	39	-	ns
E_{on}	Turn-on Switching Loss		-	1.44	-	mJ
E_{off}	Turn-off Switching Loss		-	0.55	-	mJ
E_{ts}	Total Switching Loss		-	1.99	-	mJ
$t_{d(on)}$	Turn-on Delay Time		-	65	-	ns
t_r	Turn-on Rise Time	$I_C=40\text{A}, V_{CC}=600\text{V}, V_{GE}=15\text{V}, R_G=10\Omega, \text{Inductive Load, } T_C=150\text{ }^\circ\text{C}$	-	45	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	292	-	ns
t_f	Turn-off Fall Time		-	75	-	ns
E_{on}	Turn-on Switching Loss		-	2.43	-	mJ
E_{off}	Turn-off Switching Loss		-	1.09	-	mJ
E_{ts}	Total Switching Loss		-	3.52	-	mJ
C_{ies}	Input Capacitance	$V_{GE}=0\text{V}, V_{CE}=25\text{V}, f=1.0\text{MHz}$	-	3942	-	pF
C_{res}	Reverse Transfer Capacitance		-	72	-	pF
C_{oes}	Output Capacitance		-	72	-	pF
Q_g	Total Gate Charge	$I_C=40\text{A}, V_{CC}=600\text{V}, V_{GE}=15\text{V}$	-	204	-	nC
Q_{ge}	Gate to Emitter Charge		-	34	-	nC
Q_{gc}	Gate to Collector Charge		-	94	-	nC
tsc	Short Circuit Withstand Time	$V_{CC}=600\text{V}, V_{GE}=15\text{V}$	5	-	-	us

Typical Performance Characteristics

Fig. 1. Typical Output Characteristics

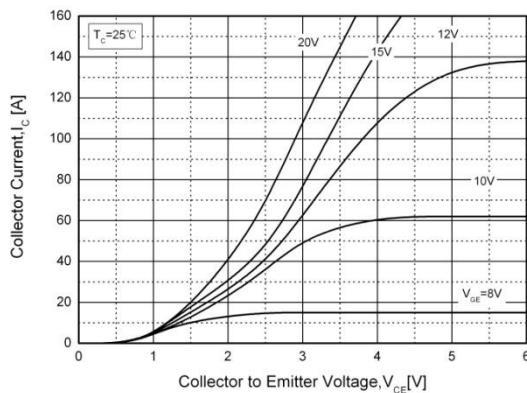


Fig. 2. Typical Saturation Voltage Characteristics

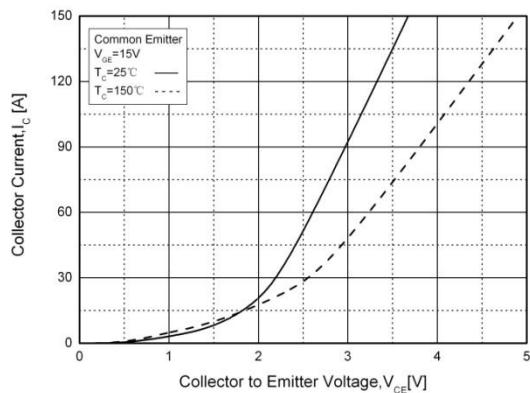


Fig. 3. Typical Transfer Characteristics

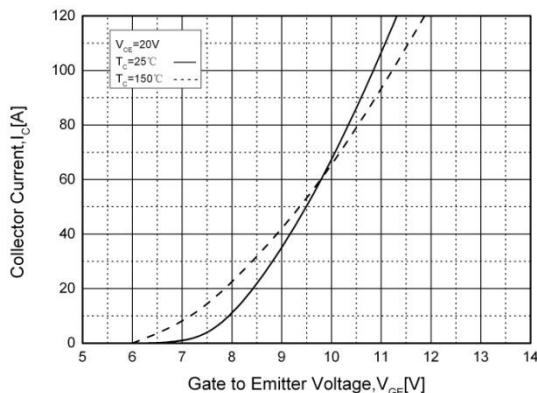


Fig. 4. Typical Saturation Voltage vs. T_c

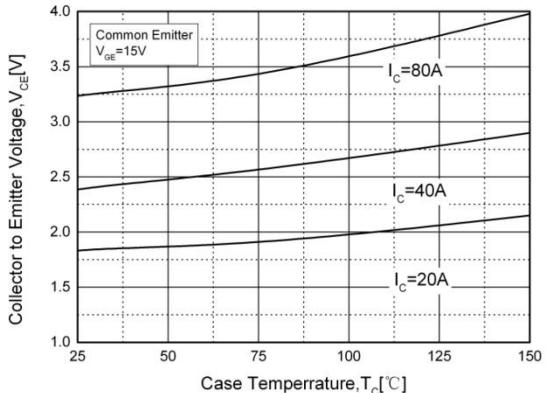


Fig. 5. Diode Forward Characteristics

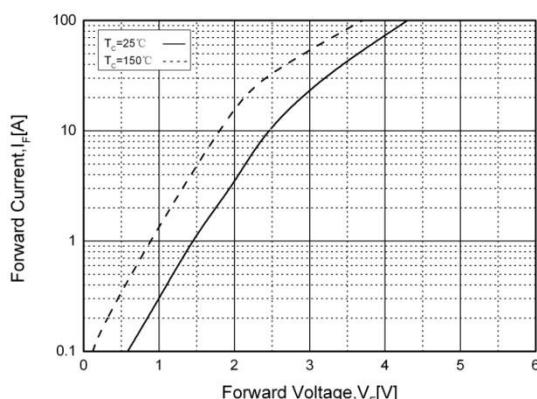
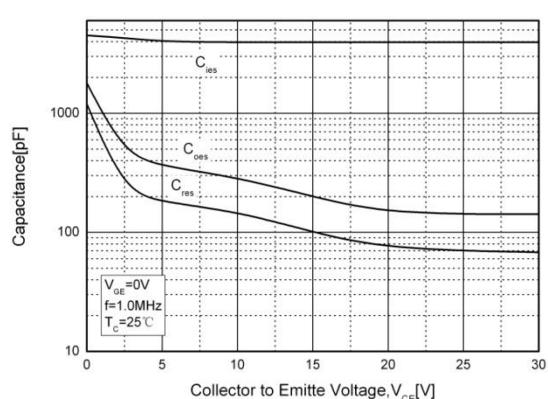


Fig. 6. Typical Capacitance Characteristics



Typical Performance Characteristics

Fig. 7. Turn-on Characteristics vs. R_G

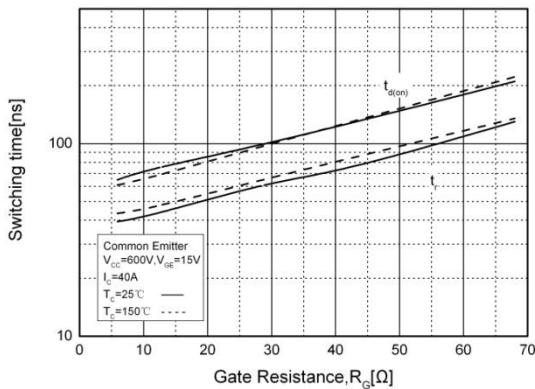


Fig. 8. Turn-off Characteristics vs. R_G

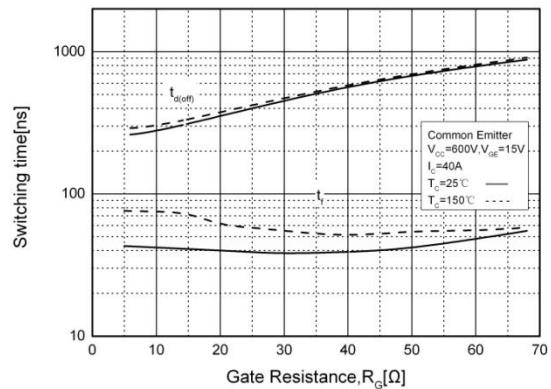


Fig. 9. Switching Loss vs. R_G

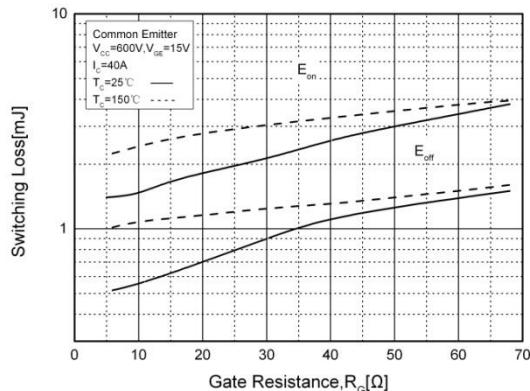


Fig. 10. Turn-on Characteristics vs. I_C

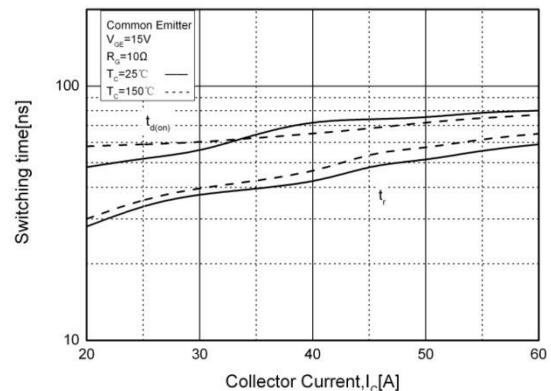


Fig. 11. Turn-off Characteristics vs. I_C

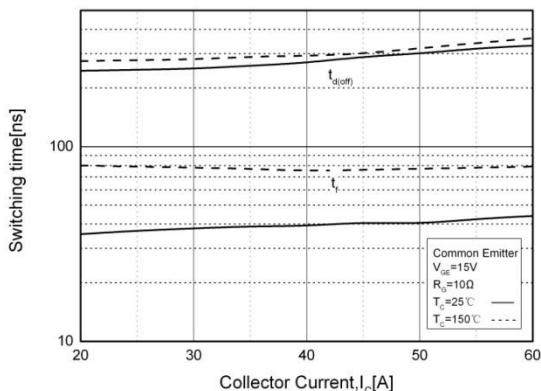
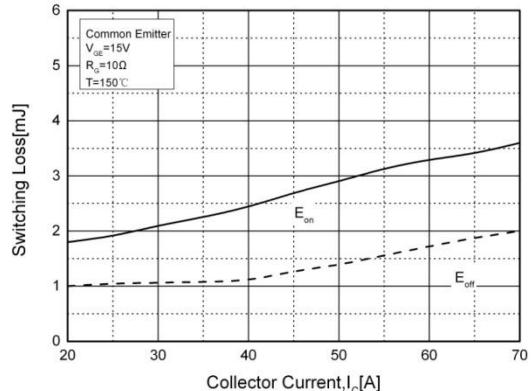


Fig. 12. Switching Loss vs. I_C



Package Dimensions

TO-264

(Dimensions in Millimeters)

